APPENDIX SHOWING MARKUPS OF AMENDMENTS

IN THE SPECIFICATION:

Page 1, after the title and prior to the background section, add the paragraph:

This application is a divisional of application 09/825,418, filed 3 April 2001, a Convention application based on Japanese applications 101756 and 101765, both filed 4 April 2000.

IN THE CLAIMS:

1. (Amended.) A wiring board, comprising:
an insulative base material;
conductor patterns formed thereon; ~~and~~
magnetic thin films formed on at least one of said conductor patterns; and
said magnetic thin films being formed with an insulation layer interposed therebetween, that covers the entirety of the surface of said wiring board on which said conductor patterns are formed.

Cancel claim 3.

19. (Amended.) A wiring board, comprising:
a board of at least one layer comprising a conductor part, said conductor part comprising signal line conductor patterns; and
magnetic thin films deployed at least on part of said board or said conductor part, and being deployed with an insulation layer interposed therebetween so as to cover said conductor pattern.

Cancel claims 20-22.

23. (Amended.) The wiring board according to claim ~~22~~ 19, wherein said magnetic thin film is formed on said signal line conductor patterns.

24. (Amended.) The wiring board according to claim ~~22~~ 19, wherein said magnetic thin films are formed so as to be separated from signal line conductor patterns in portions where said signal line conductor patterns are not formed.

Cancel claim 25.

26. (Amended.) The wiring board according to claim ~~22~~ 19, wherein said magnetic thin film is fabricated by at least one method of sputtering and vapor deposition.

27. (Amended.) The wiring board according to claim ~~22~~ 19, wherein said magnetic thin film has a thickness with a range of 0.3 μm to 20 μm.

28. (Amended.) The wiring board according to claim ~~22~~ 19, wherein said wiring board is a multilayer printed wiring board comprising a structure of at least 3 layers.

29. (Amended.) The wiring board according to claim ~~22~~ 19, wherein said magnetic thin film is configured of a magnetic loss material represented by M-X-Y, where M is at least one of Fe, Co, and Ni, Y is at least one of F, N, and O, and X is at least one element other than M or Y,

said magnetic loss material is a broad-band magnetic loss material in the which maximum value of μ''_{max} of loss factor μ" that is the imaginary component in the complex permeability of said magnetic loss material exists within a frequency range of 100 MHz to 10 GHz, and

a relative bandwidth bwr is not smaller than 150% where the relative bandwidth bwr is obtained by extracting a frequency bandwidth between two frequencies at which the value of μ" is 50% of the maximum μ''_{max} and normalizing the frequency bandwidth at the center frequency thereof.

32. (Amended.) The wiring board according to claim ~~22~~ 19, wherein said magnetic thin film is configured of a magnetic loss material represented by M-X-Y, where M is at least one of Fe, Co, and Ni, Y is at least one of F, N, and O, and X is at least one element other than M or Y,

said magnetic loss material is a narrow-band magnetic loss material in the which maximum value of μ''_{max} of loss factor μ" that is the imaginary component in the complex permeability of said magnetic loss material exists within a frequency range of 100 MHz to 10 GHz, and

a relative bandwidth bwr is not smaller than 200% where the relative bandwidth bwr is obtained by extracting a frequency bandwidth between two frequencies at which the value of μ" is 50% of the maximum μ''_{max} and normalizing the frequency bandwidth at the center frequency thereof.